



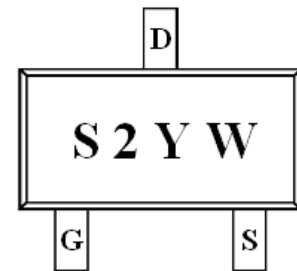
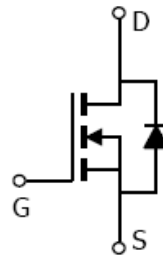
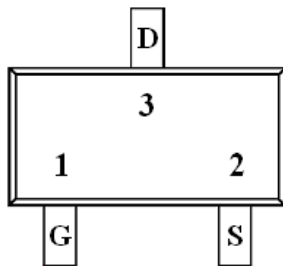
### General Description

AFN2302AS, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge. These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

### Features

- 20V/3.6A,  $R_{DS(ON)}=70m\Omega@V_{GS}=4.5V$
- 20V/3.1A,  $R_{DS(ON)}=90m\Omega@V_{GS}=2.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23 package design

### Pin Description ( SOT-23 )



### Application

- Portable Equipment
- Battery Powered System
- Net Working System

### Pin Define

| Pin | Symbol | Description |
|-----|--------|-------------|
| 1   | G      | Gate        |
| 2   | S      | Source      |
| 3   | D      | Drain       |

### Ordering Information

| Part Ordering No. | Part Marking | Package | Unit        | Quantity |
|-------------------|--------------|---------|-------------|----------|
| AFN2302ASS23RG    | S2YW         | SOT-23  | Tape & Reel | 3000 EA  |

- ※ S2 parts code
- ※ Y year code ( 0 ~ 9 )
- ※ W week code ( A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52 )
- ※ AFN2302ASS23RG : 7" Tape & Reel ; Pb- Free ; Halogen- Free



### Absolute Maximum Ratings

(T<sub>A</sub>=25°C Unless otherwise noted)

| Parameter                                       | Symbol           | Typical              | Unit |
|---|------------------|----------------------|------|
| Drain-Source Voltage                            | V <sub>DSS</sub> | 20                   | V    |
| Gate –Source Voltage                            | V <sub>GSS</sub> | ±12                  | V    |
| Continuous Drain Current(T <sub>J</sub> =150°C) | I <sub>D</sub>   | T <sub>A</sub> =25°C | 3.6  |
|   |                  | T <sub>A</sub> =70°C | 2.0  |
| Pulsed Drain Current                            | I <sub>DM</sub>  | 10                   | A    |
| Continuous Source Current(Diode Conduction)     | I <sub>S</sub>   | 1.6                  | A    |
| Power Dissipation                               | P <sub>D</sub>   | T <sub>A</sub> =25°C | 1.25 |
|   |                  | T <sub>A</sub> =70°C | 0.8  |
| Operating Junction Temperature                  | T <sub>J</sub>   | 150                  | °C   |
| Storage Temperature Range                       | T <sub>STG</sub> | -55/150              | °C   |
| Thermal Resistance-Junction to Ambient          | R <sub>θJA</sub> | 120                  | °C/W |

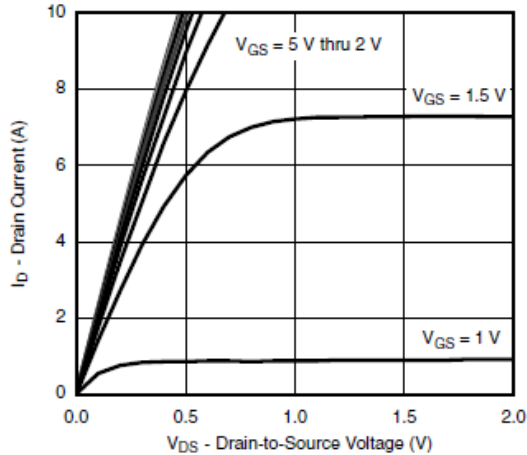
### Electrical Characteristics

(T<sub>A</sub>=25°C Unless otherwise noted)

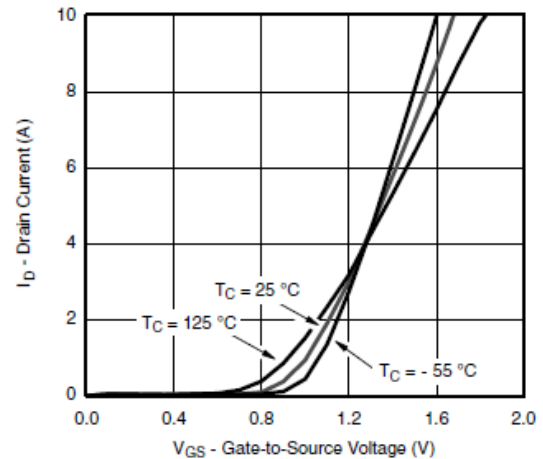
| Parameter                       | Symbol               | Conditions   | Min. | Typ  | Max. | Unit |
|---------------------------------|----------------------|--|------|------|------|------|
| <b>Static</b>                   |                      |  |      |      |      |      |
| Drain-Source Breakdown Voltage  | V <sub>(BR)DSS</sub> | V <sub>GS</sub> =0V, I <sub>D</sub> =250uA   | 20   |      |      | V    |
| Gate Threshold Voltage          | V <sub>GS(th)</sub>  | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA   | 0.5  |      | 1.0  |      |
| Gate Leakage Current            | I <sub>GSS</sub>     | V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V   |      |      | ±100 | nA   |
| Zero Gate Voltage Drain Current | I <sub>DSS</sub>     | V <sub>DS</sub> =16V, V <sub>GS</sub> =0V  |      |      | 1    | uA   |
|                                 |                      | V <sub>DS</sub> =16V, V <sub>GS</sub> =0V<br>T <sub>J</sub> =85°C  |      |      | 10   |      |
| On-State Drain Current          | I <sub>D(on)</sub>   | V <sub>DS</sub> ≥5V, V <sub>GS</sub> =4.5V   | 6    |      |      | A    |
|                                 |                      | V <sub>DS</sub> ≥5V, V <sub>GS</sub> =2.5V   | 4    |      |      |      |
| Drain-Source On-Resistance      | R <sub>DS(on)</sub>  | V <sub>GS</sub> =4.5V, I <sub>D</sub> =2.4A  |      | 48   | 70   | mΩ   |
|                                 |                      | V <sub>GS</sub> =2.5V, I <sub>D</sub> =2.0A  |      | 58   | 90   |      |
| Forward Transconductance        | g <sub>FS</sub>      | V <sub>DS</sub> =5V, I <sub>D</sub> =3.6A  |      | 10   |      | S    |
| Diode Forward Voltage           | V <sub>SD</sub>      | I <sub>S</sub> =1.6A, V <sub>GS</sub> =0V  |      | 0.7  | 1.2  | V    |
| <b>Dynamic</b>                  |                      |  |      |      |      |      |
| Total Gate Charge               | Q <sub>g</sub>       | V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V<br>I <sub>D</sub> ≧3.6A  |      | 3.5  | 10   | nC   |
| Gate-Source Charge              | Q <sub>gs</sub>      |  |      | 0.65 |      |      |
| Gate-Drain Charge               | Q <sub>gd</sub>      |  |      | 0.45 |      |      |
| Input Capacitance               | C <sub>iss</sub>     | V <sub>DS</sub> =10V, V <sub>GS</sub> =0V<br>f=1MHz  |      | 300  |      | pF   |
| Output Capacitance              | C <sub>oss</sub>     |  |      | 68   |      |      |
| Reverse Transfer Capacitance    | C <sub>rss</sub>     |  |      | 40   |      |      |
| Turn-On Time                    | t <sub>d(on)</sub>   | V <sub>DD</sub> =10V, R <sub>L</sub> =5.5Ω<br>I <sub>D</sub> ≧3.6A, V <sub>GEN</sub> =4.5V<br>R <sub>G</sub> =6Ω |      | 12   | 25   | ns   |
|                                 | t <sub>r</sub>       |  |      | 36   | 60   |      |
| Turn-Off Time                   | t <sub>d(off)</sub>  |  |      | 34   | 60   |      |
|                                 | t <sub>f</sub>       |  |      | 10   | 25   |      |



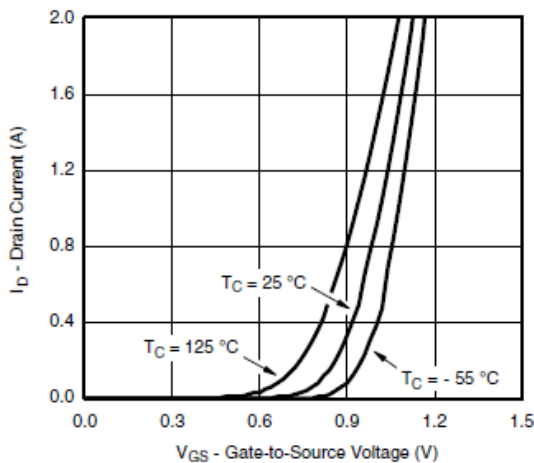
## Typical Characteristics



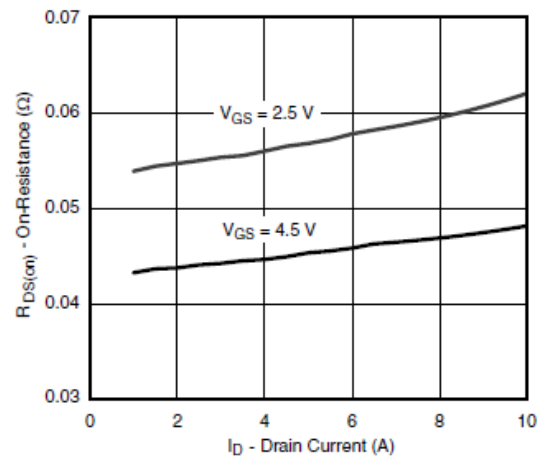
Output Characteristics



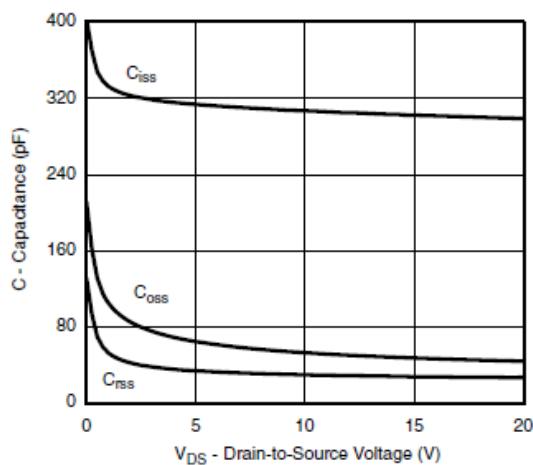
Transfer Characteristics



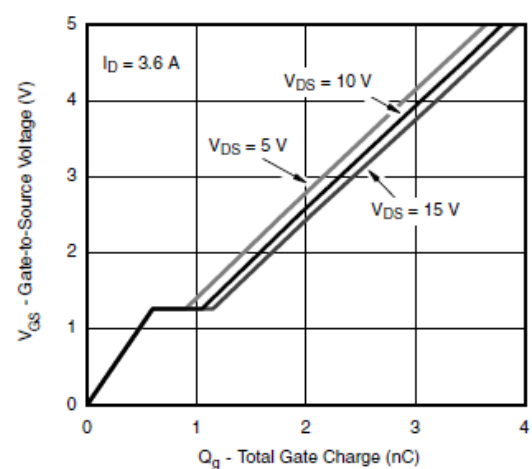
Transfer Characteristics



On-Resistance vs. Drain Current



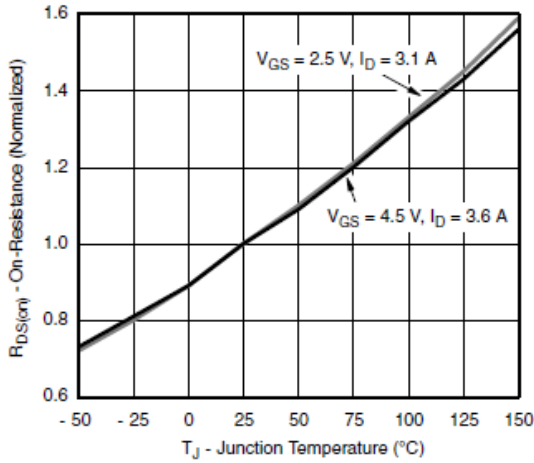
Capacitance



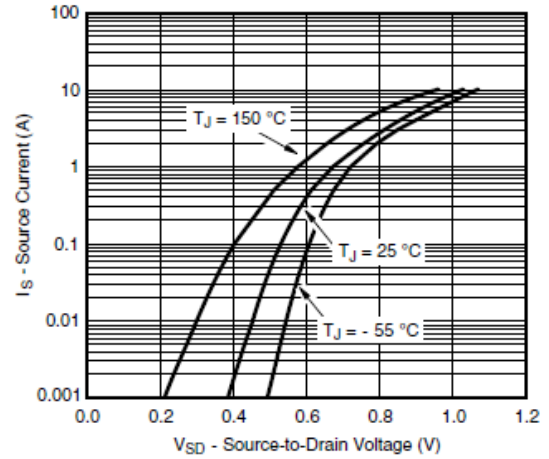
Gate Charge



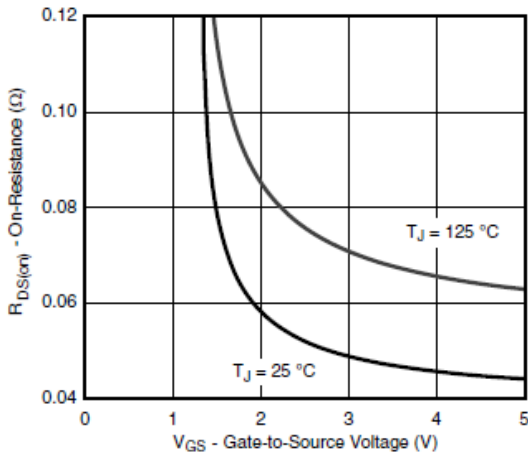
**Typical Characteristics**



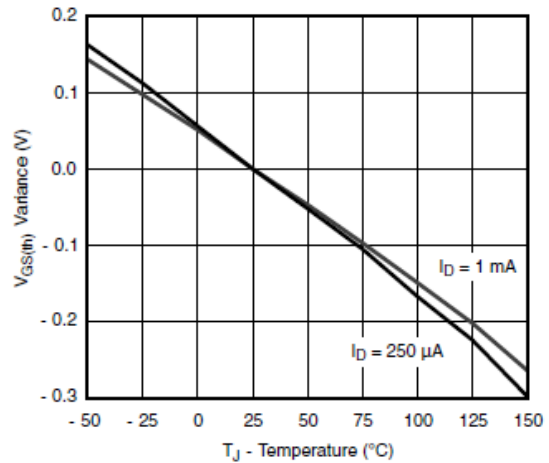
**On-Resistance vs. Junction Temperature**



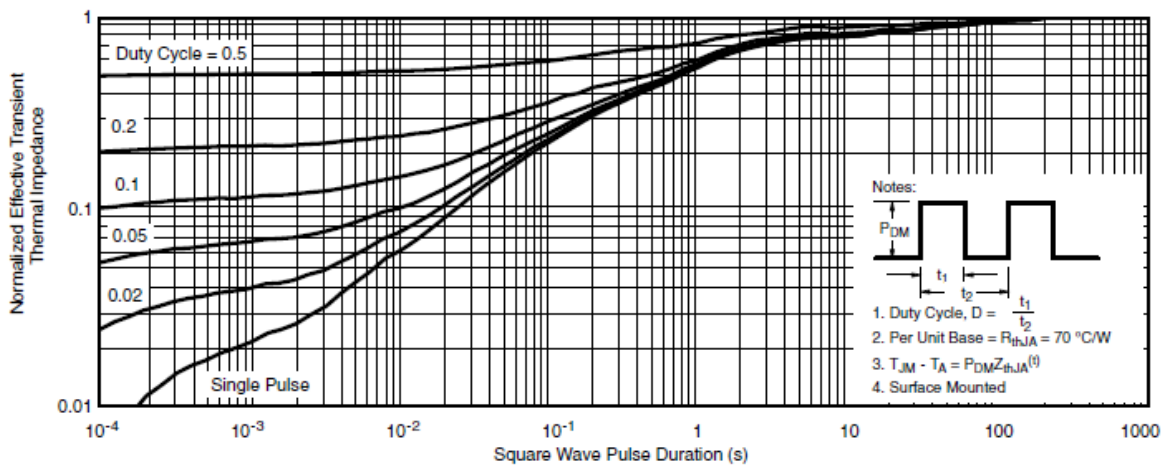
**Source-Drain Diode Forward Voltage**



**On-Resistance vs. Gate-to-Source Voltage**



**Threshold Voltage**

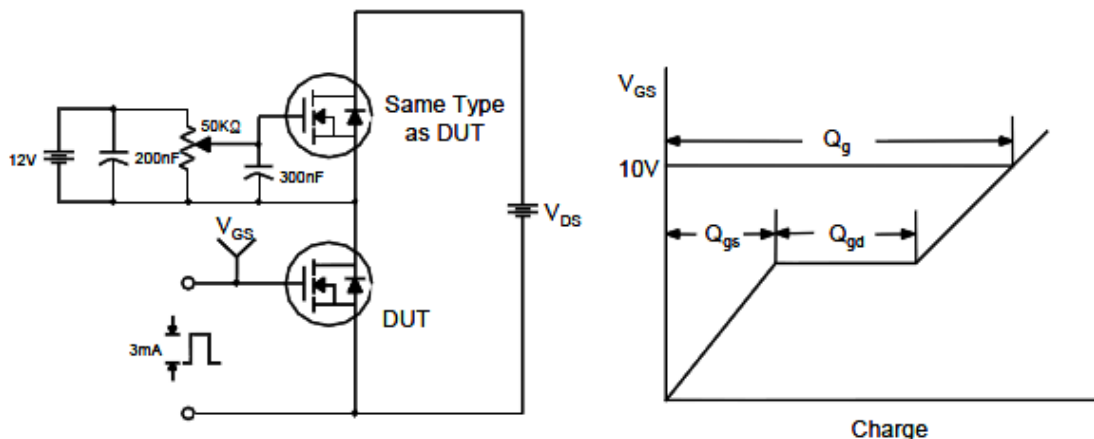


**Normalized Thermal Transient Impedance, Junction-to-Ambient**

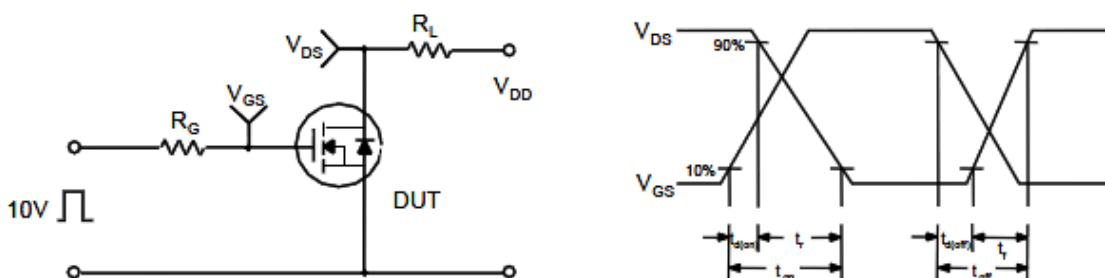


**Typical Characteristics**

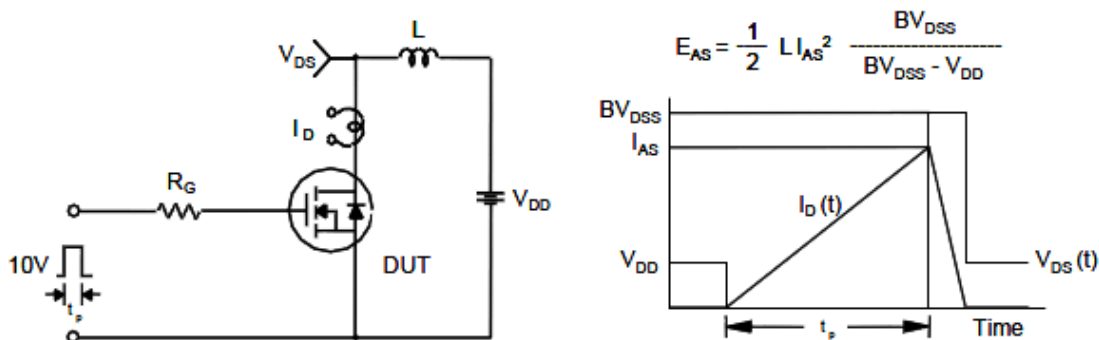
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

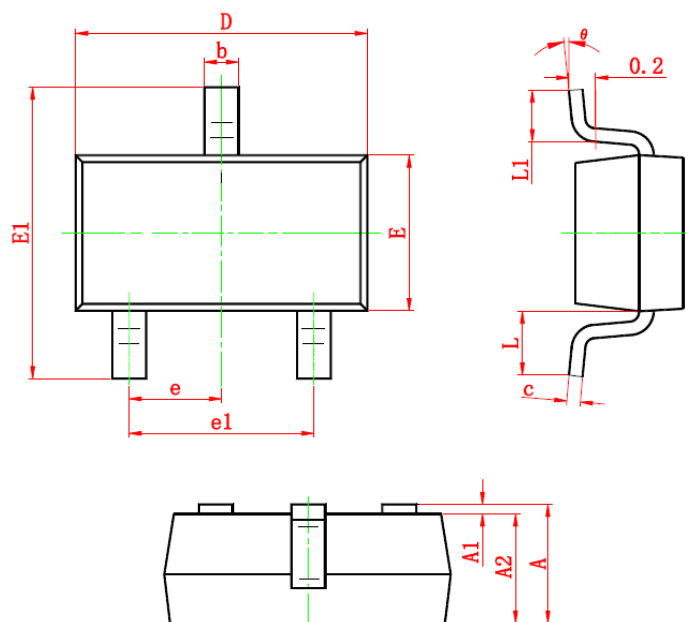


Unclamped Inductive Switching Test Circuit & Waveforms





**Package Information ( SOT-23 )**



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 0.900                     | 1.200 | 0.035                | 0.043 |
| A1     | 0.000                     | 0.100 | 0.000                | 0.004 |
| A2     | 0.900                     | 1.100 | 0.035                | 0.039 |
| b      | 0.300                     | 0.500 | 0.012                | 0.020 |
| c      | 0.080                     | 0.150 | 0.003                | 0.006 |
| D      | 2.800                     | 3.000 | 0.110                | 0.118 |
| E      | 1.200                     | 1.400 | 0.047                | 0.055 |
| E1     | 2.250                     | 2.550 | 0.089                | 0.100 |
| e      | 0.950 TYP                 |       | 0.037 TYP            |       |
| e1     | 1.800                     | 2.000 | 0.071                | 0.079 |
| L      | 0.550 REF                 |       | 0.022 REF            |       |
| L1     | 0.300                     | 0.500 | 0.012                | 0.020 |
| θ      | 0°                        | 8°    | 0°                   | 6°    |

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